

Amendment and Response

6770200-0001

AMENDMENT

Applicants hereby amend the claims of the application in the manner shown below. The Patent Office is respectfully requested to enter these amendments.

IN THE CLAIMS

Please cancel claims 1, 2, 3 and 82 of the application. (Claims 4 and 40-81 had already been canceled by Applicants in an Amendment and Response dated May 11, 2009.)

Please also amend claims 5, 6, 7, 8, 12, 13, 15, 20, 22, 23, 26, 36, 37 and 39 of the application in the manner shown below, and add new claims 83 and 84 to the application.

Claims 1-4 (Canceled)

5. (Currently Amended) The A composition of claim 1 for application to a material comprising:

- (a) at least one alkaline metal inorganic salt, wherein the alkaline metal inorganic salt is present in the composition in an amount ranging from about 5% to about 45% by weight;
- (b) at least one potassium salt of an organic acid, wherein the potassium salt of an organic acid is present in the composition in an amount ranging from about 1% to about 72% by weight;
- (c) optionally, at least one boron-containing compound, wherein the boron-containing compound is present in the composition in an amount ranging from about 0% to about 10% by weight;
- (d) optionally, at least one surfactant, wherein the surfactant is present in the composition in an amount ranging from about 0% to about 5% by weight;
- (e) at least one microbe-inhibiting compound, wherein the microbe-inhibiting compound is present in the composition in an amount ranging from about 0.1% to about 6% by weight;

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(f) at least one detection component, wherein the detection component is present in the composition in an amount ranging from about 0.01% to about 10% 3% by weight such that it permits a determination of whether or not the composition has been applied to the material; and

(g) an aqueous liquid, wherein the aqueous liquid is present in the composition in an amount that brings the percent weight of the composition to 100%;

wherein the composition has a pH ranging from about 7.1 to about 14, and wherein the composition, when applied to the material, reduces the amount of burning that occurs to the material, or the amount or density of smoke produced by the material, when the material is subsequently exposed to fire, and when the composition is applied to a material prior to, during or after the material being exposed to conditions favorable to the growth of microbes, reduces, inhibits or prevents the growth of microbes on the material when the material is exposed to conditions favorable to the growth of microbes.

6. (Currently Amended) The A composition of claim 1 for application to a material comprising:

(a) at least one alkaline metal inorganic salt, wherein the alkaline metal inorganic salt is present in the composition in an amount ranging from about 5% to about 45% by weight;

(b) at least one potassium salt of an organic acid, wherein the potassium salt of an organic acid is present in the composition in an amount ranging from about 1% to about 72% by weight;

(c) optionally, at least one boron-containing compound, wherein the boron-containing compound is present in the composition in an amount ranging from about 0% to about 10% by weight;

(d) optionally, at least one surfactant, wherein the surfactant is present in the composition in an amount ranging from about 0% to about 5% by weight;

(e) at least one microbe-inhibiting compound, wherein the microbe-inhibiting compound is present in the composition in an amount ranging from about 0.1% to about 6% by weight;

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(f) at least one detection component, wherein the detection component is present in the composition in an amount ranging from about 0.01% to about 10% by weight such that it permits a determination of whether or not the composition has been applied to the material; and

(g) an aqueous liquid, wherein the aqueous liquid is present in the composition in an amount that brings the percent weight of the composition to 100%;

wherein the composition has a pH ranging from about 7.1 to about 14, and wherein the composition, when applied to the material, reduces the amount of burning that occurs to the material, or the amount or density of smoke produced by the material, when the material is subsequently exposed to fire, and when the composition is applied to a material prior to, during or after the material being exposed to conditions favorable to the growth of microbes, reduces, inhibits or prevents the growth of microbes on the material when the material is exposed to conditions favorable to the growth of microbes.

7. **(Currently Amended)** The composition of claim 6 wherein the microbe-inhibiting compound functions as the detection component, ~~or wherein the microbe-inhibiting compound is different from the detection component and the detection component is present in an amount ranging from about 0.01% to about 10% by weight.~~

8. **(Currently Amended)** The composition of ~~claim 7~~ claim 6 wherein the alkaline metal inorganic salt is present in an amount ranging from about 20% to about 42% by weight.

9. **(Original)** The composition of claim 8 wherein the potassium salt of an organic acid is present in an amount ranging from about 2% to about 60% by weight.

10. **(Original)** The composition of claim 9 wherein the potassium salt of an organic acid is present in an amount ranging from about 2% to about 40% by weight.

11. **(Original)** The composition of claim 10 wherein the potassium salt of an organic acid is present in an amount ranging from about 8% to about 15% by weight.

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12. **(Currently Amended)** The composition of claim 11 wherein the composition contains a boron-containing compound, and wherein the boron-containing compound is present in an amount ranging from about 0.4% to about 8% by weight.

13. **(Currently Amended)** The composition of claim 12 wherein the composition contains a surfactant, and wherein the surfactant is present in an amount ranging from about 0.3% to about 3% by weight.

14. **(Original)** The composition of claim 13 wherein the microbe-inhibiting compound is present in an amount ranging from about 0.1% to about 3% by weight.

15. **(Currently Amended)** The composition of claim 5 wherein the detection component is present in an amount ranging from about 0.01% to about 3% 2% by weight.

16. **(Original)** The composition of claim 14 wherein the detection component is present in an amount ranging from about 0.01% to about 3% by weight.

17. **(Original)** The composition of claim 16 wherein the boron-containing compound is present in an amount ranging from about 1% to about 6% by weight.

18. **(Original)** The composition of claim 17 wherein the surfactant is present in an amount ranging from about 0.5% to about 0.7% by weight.

19. **(Original)** The composition of claim 15 wherein the detection component is present in an amount of about 0.7%.

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20. **(Currently Amended)** The composition of ~~claim 7~~ claim 6 wherein the alkaline metal inorganic salt is potassium carbonate, potassium carbonate sesquihydrate, potassium gluconate, potassium citrate, potassium sorbate, potassium bromide, potassium chloride, potassium chromate, potassium fluoride, potassium iodide, potassium salicylate, potassium selenate, potassium silicate, potassium thioantimonate, potassium sulfide, potassium sulfate, potassium thiosulfate, potassium tartrate, potassium phosphate, sodium acetate, sodium carbonate, sodium formate, sodium sorbate, sodium sulfate, sodium tartrate, sodium nitrate, sodium phosphate, sodium gluconate, sodium citrate, sodium sorbate, lithium sulfate, lithium tartrate, lithium nitrate, lithium phosphate, rubidium acetate, rubidium carbonate, rubidium sulfate, cesium acetate, cesium sulfate or a combination of one or more of the foregoing.

21. **(Original)** The composition of claim 20 wherein the potassium salt of an organic acid is potassium acetate, potassium formate, potassium tartrate, potassium citrate, potassium sorbate, potassium lactate or potassium gluconate.

22. **(Currently Amended)** The composition of claim 21 wherein the composition contains a boron-containing compound, and wherein the boron-containing compound is ammonium borate, sodium borate, potassium borate, calcium borate, potassium tetraborate or potassium pentaborate.

23. **(Currently Amended)** The composition of claim 22 wherein the composition contains a surfactant, and wherein the surfactant is isodecyloxypropyl dihydroxy methyl ammonium chloride, cetyl trimethyl ammonium bromide, telomer B monoether, alkyl imino acid, monosodium salt, B-alanine, N-(2-carboxyethyl)-N-3 decyloxy propyl monosodium salt, Neodol 25-7, Neodol 25-9, alkyloxypolyethoxeneoxyethanol, Tergitol 15-S-7, Nonylphenol, NP-9 Ethoxalted nonylphenol or Octyphenol.

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24. **(Previously Presented)** The composition of claim 23 wherein the microbe-inhibiting compound is 2-pyridinethiol-1-oxide, sodium salt, 3-iodo-2-propynyl butyl carbamate, disodium cyanodithiolimidocarbonate, potassium N-methyldithiocarbamate, ethanol, 2,2'-(cocoimino)-bis, salt with phosphoric acid, bis (2-ethylhexyl ester (1:1), ethanol, 2,2'-(cocoimino)-bis, salt with phosphoric acid, mono (2-ethylhexyl) ester (1:1), phosphoric acid, mono (2-ethylhexyl) ester, bis(tri-N-butyl)oxide, ortho-phenyl phenol, potassium iodide, ammonium iodide, potassium iodate, ammonium iodate, 10-10 oxybisphenoxyarsine, octadecyl.nodim.ethyltrihydroxy silypropyl ammonium chloride or 3-(trimethoxysilyl)propyloctadecyldimethyl ammonium chloride.

25. **(Original)** The composition of claim 24 wherein the microbe-inhibiting compound is 2-pyridinethiol-1-oxide, sodium salt.

26. **(Currently Amended)** The composition of ~~claim 5~~ claim 6 wherein the detection component is 3-iodo-2-propynyl butyl carbamate, zirconia, selenium dioxide, zirconium acetate or a boron-containing compound.

27. **(Original)** The composition of claim 24 wherein the detection component is 3-iodo-2-propynyl butyl carbamate, zirconia, selenium dioxide, zirconium acetate or a boron-containing compound.

28. **(Original)** The composition of claim 27 wherein the alkaline metal inorganic salt is potassium carbonate.

29. **(Original)** The composition of claim 28 wherein the potassium salt of an organic acid is potassium acetate.

30. **(Original)** The composition of claim 29 wherein the boron-containing compound is potassium tetraborate or potassium pentaborate.

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31. **(Original)** The composition of claim 30 wherein the surfactant is isodecyloxypropyl dihydroxy methyl ammonium chloride.

32. **(Original)** The composition of claim 26 wherein the detection component is 3-iodo-2-propynyl butyl carbamate or a boron-containing compound.

33. **(Original)** The composition of claim 31 wherein the detection component is 3-iodo-2-propynyl butyl carbamate or a boron-containing compound.

34. **(Original)** The composition of claim 33 wherein the microbe-inhibiting compound is 3-iodo-2-propynyl butyl carbamate, and the 3-iodo-2-propynyl butyl carbamate also functions as the detection component.

35. **(Original)** The composition of claim 34 wherein the pH of the composition is about 11 or higher.

36. **(Currently Amended)** The A composition of claim 1 for application to a material wherein the composition contains comprising:

- (a) potassium carbonate in the an amount of about 25% by weight;
- (b) potassium acetate in the an amount of about 13% by weight; and
- (c) either potassium tetraborate or potassium pentaborate in the an amount of about 2% by weight;
- (d) optionally, at least one surfactant, wherein the surfactant is present in the composition in an amount ranging from about 0% to about 5% by weight;
- (e) at least one microbe-inhibiting compound, wherein the microbe-inhibiting compound is present in the composition in an amount ranging from about 0.1% to about 6% by weight;
- (f) optionally, at least one detection component, wherein the detection component is present in the composition in an amount ranging from about 0% to about 10% by weight; and

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(g) with the remaining weight being water, wherein the water is present in the composition in an amount that brings the percent weight of the composition to 100%;

wherein the composition and has a pH of about 11 or higher, and wherein the composition, when applied to the material, reduces the amount of burning that occurs to the material, or the amount or density of smoke produced by the material, when the material is subsequently exposed to fire, and when the composition is applied to a material prior to, during or after the material being exposed to conditions favorable to the growth of microbes, reduces, inhibits or prevents the growth of microbes on the material when the material is exposed to conditions favorable to the growth of microbes.

37. (Currently Amended) The composition of claim 36 wherein the composition additionally contains isodecyloxypropyl dihydroxy methyl ammonium chloride in an amount of about 0.5% by weight, and wherein the microbe-inhibiting compound is 2-pyridinethiol-1-oxide, sodium salt in an amount ranging from about 0.4% to about 0.9% by weight, ~~with the remainder of the weight percent of the composition being water.~~

38. (Previously Presented) The composition of claim 37 wherein the 2-pyridinethiol-1-oxide, sodium salt is present in an amount of about 0.5% by weight.

39. (Currently Amended) The composition of claim 36 wherein the composition additionally contains isodecyloxypropyl dihydroxy methyl ammonium chloride in an amount of about 0.5% by weight, and wherein the microbe-inhibiting compound is 3-iodo-2-propynyl butyl carbamate in an amount of about 0.7% by weight, ~~with the remainder of the weight percent of the composition being water.~~

Claims 40-82 (Canceled)

83. (New) The composition of claim 6 wherein the alkaline metal inorganic salt is potassium bicarbonate.

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84. (New) The composition of claim 21 wherein the boron-containing compound is potassium metaborate.